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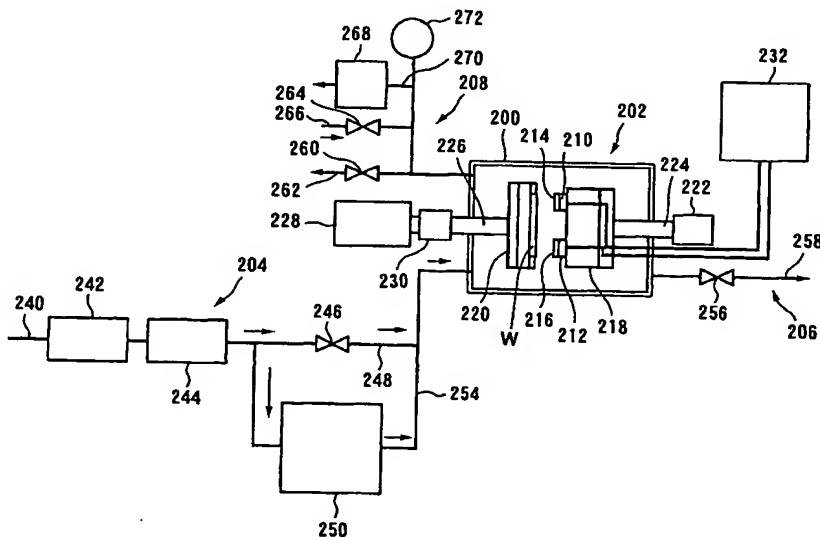
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(54) Title: ELECTROLYTIC PROCESSING APPARATUS AND ELECTROLYTIC PROCESSING METHOD



(57) Abstract: The present invention provides an electrolytic processing apparatus and an electrolytic processing method which can effectively prevent the formation of pits that would impair the quality of the processed product. The electrolytic processing apparatus including: a processing electrode (210) for processing a workpiece; a feeding electrode (212) for feeding electricity to the workpiece; a power source (232) for applying a voltage between the processing electrode (210) and the feeding electrode (212); a pressure tight system (204) for supplying a high-pressure liquid into the pressure tight container (210); and a high-pressure liquid supply system (250).

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